

REMARKS

Applicant has amended claims 1 and 4. Applicant respectfully submits that these amendments to the claims are supported by the application as originally filed and do not contain any new matter. Accordingly, the Office Action will be discussed in terms of the claims as amended.

The Examiner has rejected claims 1-4 under 35 USC 102 as being anticipated by U.S. Patent Publication No. 2003/0029033 to Hidese et al., stating that Hidese et al. discloses all of the elements of the claims and particularly discloses a method and apparatus for successively bonding chips to a plurality of chip mount portions on a substrate.

In reply thereto, Applicant has carefully reviewed Hidese et al. and respectfully submits that Hidese et al. does not disclose all of the elements of the present invention. In particular, in Applicant invention the visual field is set so that a plurality of chip mount portions or islands are imaged all at once. The imaging step is for detecting the position of bonding or mounting of the parts and for determining if the bonding parts or mounted parts are set to be executed commonly. As a result, position detection and bonding inspection are accomplished in short time in Applicant's invention and this is an advantage over the prior art.

In contrast thereto, Hidese et al. at paragraph 0038, lines 10-15, paragraph 0039 lines 10-14 and paragraph 0064, lines 3-12 disclose that in order to mount a part on a substrate, a recognition mark on a board is first imaged and then a mounting position where the part is actually to be mounted is then imaged. Accordingly, Applicant respectfully submits that Hidese et al. requires a plurality of imaging processes to be performed for detecting the mounting position for a part. As discussed above, in Applicant's invention imaging is only performed once for position detection for a part to be mounted and for the position where the bonding is executed for a part.

Still further, in Applicant's invention, the one time imaging is performed before and after bonding or mounting and only one visual field is required. As a result, high position imaging is performed and recognition of high precision detection for part positions is executable (see fifth full paragraph on page 6 and the first full paragraph on page 7 of Applicant's specification). In contrast thereto, in Hidese et al. as shown in Fig. 2A and Fig. 2B, when a plurality of different types of parts are mounted or bonded on a unit board, the imaging magnification with reference to the subject to be imaged is low compared to Applicant's invention. As a result, Applicant

respectfully submits that it is impossible to perform a high precision recognition of mount or bonding position of the parts.

As mentioned above, Applicant's invention provides an advantage which Hidese et al. cannot provide. In particular, in Applicant's invention since a plurality of imaging is not performed to do position detection and bonding inspection, there is little waste in the program which operates the CPU and as a result, high speed calculation process is possible and high speed die bonding can be achieved.

Still further and as to claim 4, in Applicant's invention a single suction part is provided on the bonding head for accomplishing bonding of the chips. In contrast thereto, in Hidese et al. a plurality of suction nozzles are provided on the transfer head, as described in claims 1 and 12 and paragraphs 0007 and 0008 of Hidese et al.

In view of the above, therefore, Applicant respectfully submits that Hidese et al. does not disclose each and every element of Applicant's invention and claims 1-4 are not anticipated thereby.

In view of the above, therefore, it is respectfully requested that this Amendment be entered, favorably considered and the case passed to issue.

Please charge any additional costs incurred by or in order to implement this Amendment or required by any requests for extensions of time to KODA & ANDROLIA DEPOSIT ACCOUNT NO. 11-1445.

Respectfully submitted,

KODA & ANDROLIA

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